

Investor & Analyst Day

July 2021







Cautionary Statement Regarding

Forward Looking Statements

This presentation contains forward-looking statements within the meaning of safe harbor provisions of the Private Securities Litigation Reform Act of 1995 relating to future events or our future performance, such as statements regarding, but are not limited to, anticipated growth opportunities and projections about our business and its future revenues, expenses and profitability. Forward-looking statements involve known and unknown risks, uncertainties and other factors that may cause our actual results, levels of activity, performance or achievements to be materially different from any future results, levels of activity, performance or achievements expressed or implied in those forward-looking statements. Factors that may affect our results, performance, circumstances or achievements include, but are not limited to, the following: catastrophic events such as the outbreak of COVID-19; increased information technology security threats and sophisticated computer crime; foreign political and economic risks; changes in U.S. trade policies; inability to protect intellectual property; open source technology exposure; failure to compete effectively or to respond to the rapid technological changes; consolidation in our industry; difficulty to predict the length and strength of any downturn or expansion period of the market we target; factors that adversely affect the pricing and demand for our product lines; dependency on a small number of large customers; dependency on a single manufacturing facility per product line; dependency on a limited number of suppliers; lengthy sales cycle and customer delays in orders; political, economic, and military instability in Israel; risks related to our convertible notes; currency fluctuations; and quarterly fluctuations in our operating results. We cannot guarantee future results, levels of activity, performance or achievements. The matters discussed in this presentation also involve risks and uncertainties summarized under the heading "Risk Factors" in Nova's Annual Report on Form 20-F for the year ended December 31, 2020 filed with the Securities and Exchange Commission on March 1, 2021.

These factors are updated from time to time through the filing of reports and registration statements with the Securities and Exchange Commission. Nova Measuring Instruments Ltd. does not assume any obligation to update the forward-looking information contained in this presentation. This presentation includes financial measures that exclude charges for amortization of acquired intangible assets, net adjustment of deferred tax assets, stock-based compensation expenses and expense related to royalty buyout agreement with the Office of the Chief Scientist and inventory write-off and are therefore not calculated in accordance with generally accepted accounting principles (GAAP). Management believes that these non-GAAP financial measures provide meaningful supplemental information regarding Nova's performance because they reflect our operational results and enhances management's and investors' ability to evaluate Nova's performance before charges or benefits considered by management to be outside Nova's ongoing operating results. The presentation of this non-GAAP financial information is not intended to be considered in isolation or as a substitute for the financial information prepared and presented in accordance with GAAP. Management believes that it is in the best interest of its investors to provide financial information that will facilitate comparison of both historical and future results and allows greater transparency to supplemental information used by management in its financial and operational decision making. A reconciliation of each GAAP to non-GAAP financial measure discussed in this presentation is contained in the accompanying financial tables.



Today's Agenda



Eitan OppenhaimPresident & CEO

Performance highlights and strategic plans



Dror DavidCFO

Financial milestones and future directions



Zohar Gil CMO & BD

Industry forecast and Nova's growth engines



Dr. Shay Wolfling CTO

It's all about technology and differentiation



Closing remarks Q&A





Performance Highlights and Strategic Plans

Eitan Oppenhaim, President & CEO





Nova is a leading innovator and a key provider of metrology solutions for advanced process control used in semiconductor manufacturing





Key Facts Post COVID

1993

Date Founded Dually Traded

Major Sites

USA & Israel

\$325M (TTM)

Revenues- Accelerated organic growth

\$480M

Gross cash reserves

25%

R&D investment in new technologies

800

HQ & global employees - hiring rally

2.8B (TTM)

Market Capsignificant growth

Resiliency

50% production output growth

3

New technologies launched

440

Patents - accelerated IP Protection





Unique PortfolioDimensional and Materials



Disruptive Technology X-Ray and Optical, HW and SW



Diversified Exposure Segments, Customers, Territories



Solid Operational Model Agility, Efficiency, Profitability



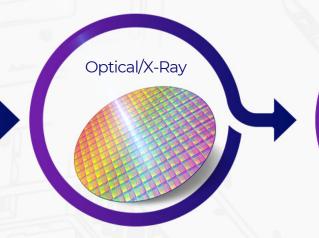
Cultural Advantage Leadership, Values, Social Responsibility



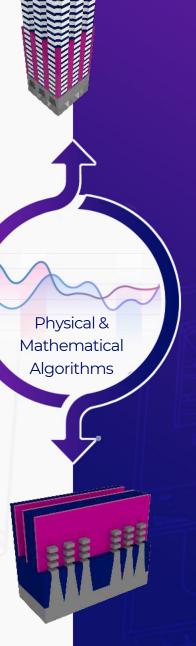




Memory Transistor











Measuring The Invisible



11.8B Transistors

150 Pairs



2020

NOM

Growing Demand

Semiconductors enable advanced digitization



Smartphone



Gaming & Video



Cryptonomy



5G



IOT Sensors



Wearables



Cloud Data

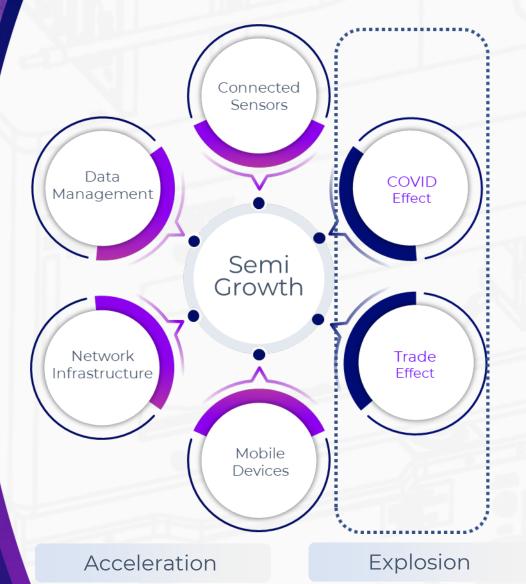


ΔΙ



Automotive





2 Beyond Capacity
Performance Demand



Enablement

Increasing Complexity = Growing Demand

Dimensional Metrology Intensity

Intensity

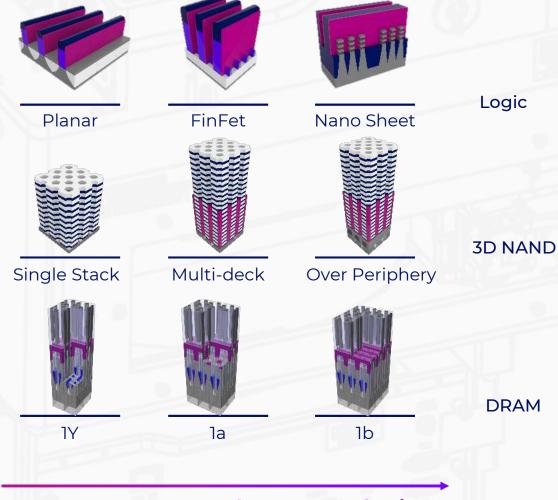
Scaled devices •—

3D profiles •—

Multiple parameters •—

Thinner films •—

Packaging •—





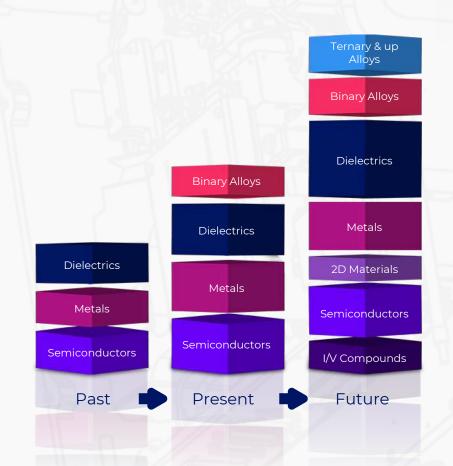




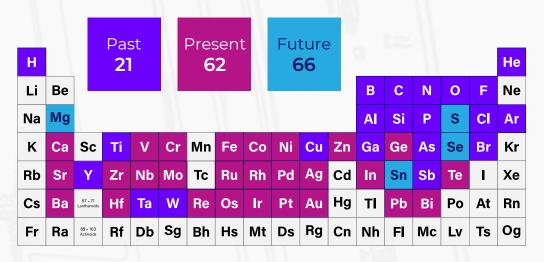
Materials Engineering

Beyond Moore's Law

Growth in IC Embedded Materials







La	Се	Pr	Nd	Pm	Sm	Eu	Gd	Tb	Dy	Но	Er	Tm	Yb	Lu
Ac	Th	Pa	U	Np	Pu	Am	Cm	Bk	Cf	Es	Fm	Md	No	Lr





Nova 500

Organic Growth

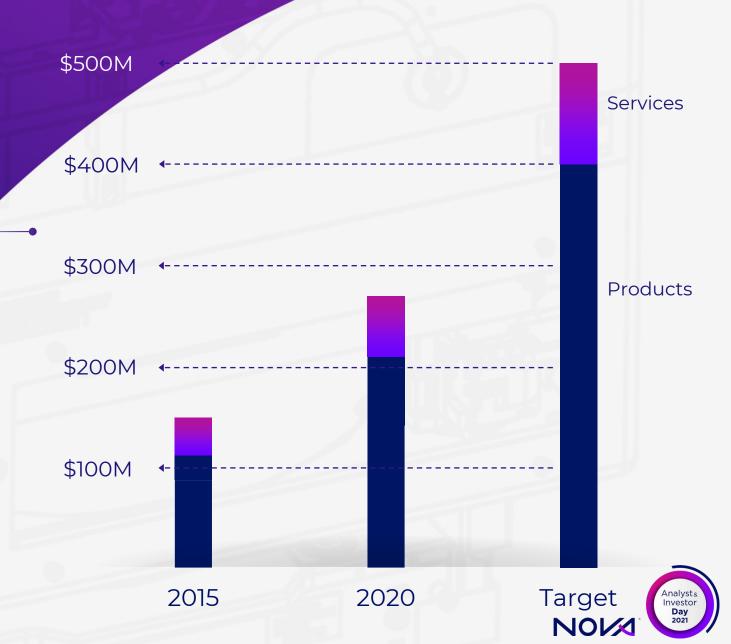
Share gains •

TAM expansion ◆

Disruptive innovation •

SW HW optimization •

Installed base utilization •



Organic Growth Engines



Differentiated technology

Innovative metrology



Physical and ML algorithms

Deep tech data-driven solutions



Service revenue

Extendibility & enhancement



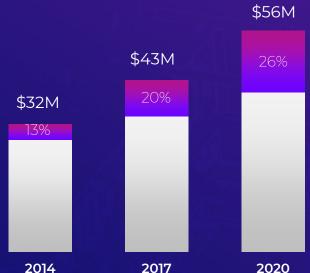
Research technologies

LAB to FAB

Total Organic Addressable Market



Investment in New Technologies (of Total R&D, Gross)



NOM

Non-GAAP Financials
Source: Gartner Research & company financial information

Inorganic Approach

Search Guidelines



Early accessLab to Fab technology



Materials Leadership



Software offering Enhancement



AdjacentProcess control markets

Screening Elements

Top line synergy

Complementary technology

Operational leverage (accretion)

Diversification within core capabilities





Financial Milestones & Future Directions

Dror David, CFO



Dror DavidChief Financial Officer



Joined Nova in 1998.

Appointed as CFO in 2005.

Beforehand, held positions of Company Controller, Vice President of Operations and Vice President of Resources in charge of finance, operations, IT and HR.

Led Nova's private placement in 2007, secondary public offering in 2010 and bond issuance in 2020.



H1 2021* Financial Performance

* Including Q2 2021 Mid-Guidance



Sustainable Profitable Annual Growth

2020 Performance

13%

Revenue CAGR

24%

Operating income CAGR

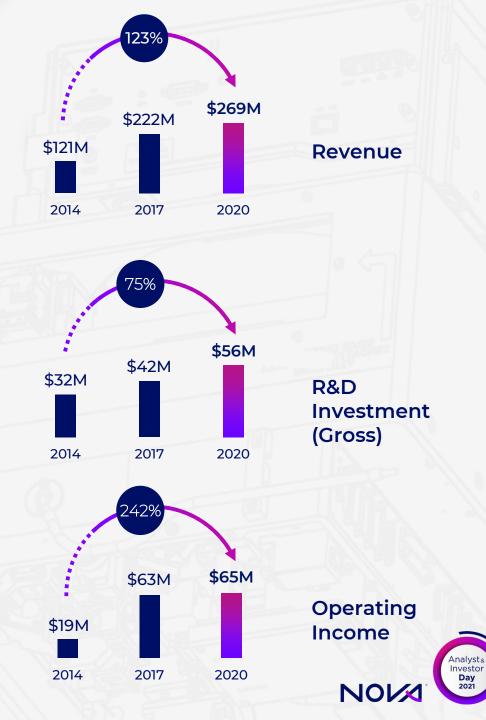
\$269M

Revenue

24%

Operating margin

CAGR – 2015-2020 Non-GAAP Financials



Financial Performance Half Year

Continuous Revenue Growth



Earnings Per Share (Non-GAAP)



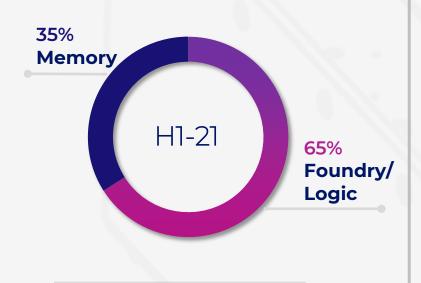
Note: Our non-GAAP measures are not meant to be considered in isolation or as a substitute for comparable GAAP measures and should be read only in conjunction with our consolidated financial statements prepared in accordance with GAAP, available on our website.



Non-GAAP Financials
* Including Q2 2021 Mid-Guidance

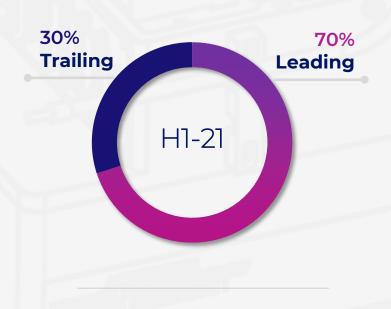


Segments



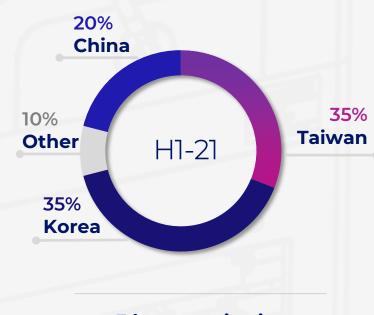
Logic/Foundry strength

Nodes



Multiple end market dynamics

Geography Revenues



3 large territories US gaining momentum



Nova 500 Financial Model



Business Tailwind



Overall TAM Growth



Market Share Gains



Software Revenues



High Value of New Technologies



Leverage Installed-Base



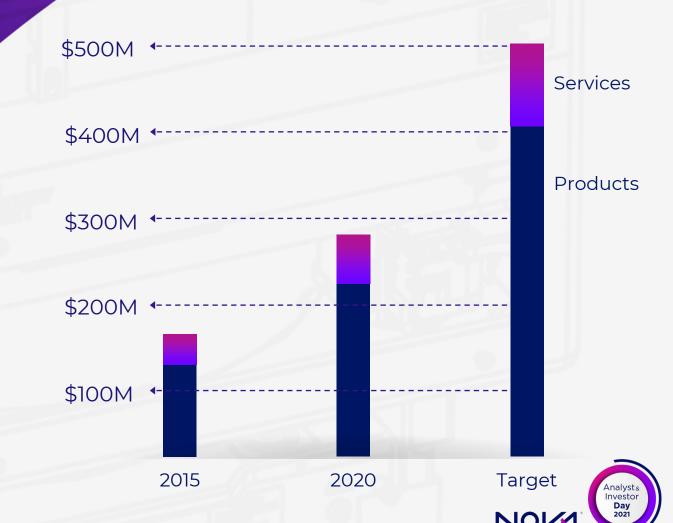
Target Revenue

Organic Growth



Source: company financial information

Non-GAAP Financials



Infrastructure Projects



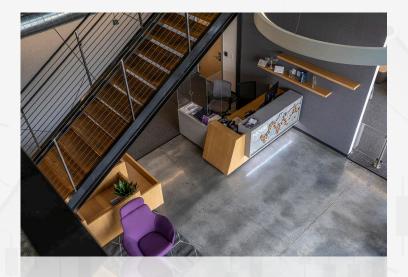
Industry 4.0 and New Cleanroom

\$12M (2022)



Global IT Networks and Applications

\$5M (2022-2023)



Locations-US, China, Ireland

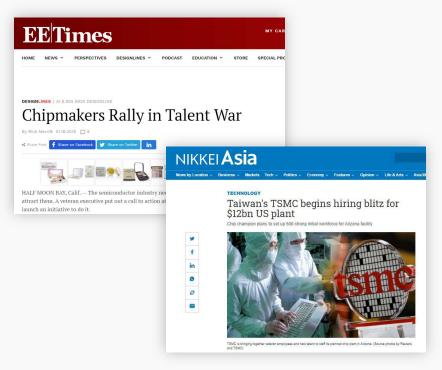
\$2M (2021-2022)



Cost Trends

Talent Costs

Increased demand for talent across territories: US | Israel | Taiwan



Macroeconomics



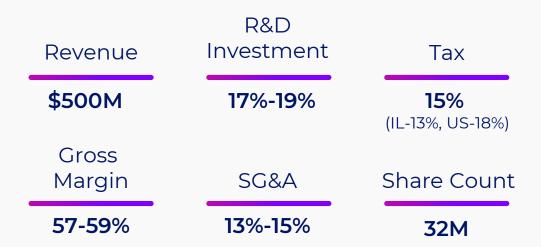
Exchange rates

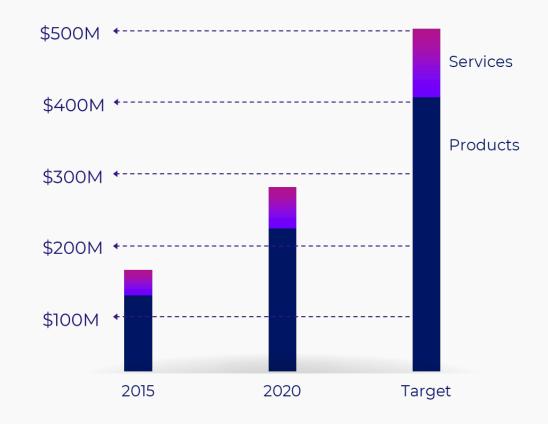


Copper prices and global manufacturing PMI



Financial Target Model





Operating Margin 26-29%

Quarterly Earnings
Power of \$1 EPS



Capital Allocation Plans



Gross Cash Reserves



Enabling inorganic growth

Facilitating continuous investment

\$200M convertible debt due 2025



Capital Allocation Plans



IT & New Sites: **\$10M**



Manufacturing Facilities: **\$12M**



Working Capital: **\$40M-\$50M**



Baseline 20% Revenue: **\$80M-\$100M**



M&A Opportunities: \$300M-\$350M



Shareholders Return



Inorganic Approach

Search Guidelines



Early accessLab to Fab technology



Materials Leadership



Software offering Enhancement



Adjacent
Process control markets

Screening Elements

Top line synergy

Complementary technology

Operational leverage (accretion)

Diversification within core capabilities

Revera Case Study

X-Ray revenue growth

X-Ray & Optical synergy

Accretion day 1 50% EPS growth Y2

Within process control

Non-GAAP Financials





Industry Forecast and Nova's Growth Engines

Zohar Gil, CMO & BD



Zohar Gil

Chief Marketing and Business Development Officer



Joined Nova in 2011.

Appointed as CMO in 2016.

Beforehand, held senior positions of marketing and business development at Nova and in Israeli high-tech companies.

Engineering and Executive MBA from Tel Aviv and Northwestern Universities.



The Revolution of Digitization and Deep Tech Innovation





Semiconductor Demand Driven By Multiple Catalysts



25% **CAGR**



VR

36% **CAGR**



Cloud Computing

> 25% **CAGR**



Industrial IoT

23% **CAGR**



Autonomous Vehicle

20 TB Per Car Daily



5G

37% **CAGR**



ΑI

42%

CAGR





2015 Data Augmentation **Productivity**



2020 **Enhanced Connectivity** Resiliency



2025 Data Efficiency Veracity



Growing Demand

Semiconductors enable advanced digitization







Cryptonomy



5G



Gaming

& Video

IOT Sensors



Wearables

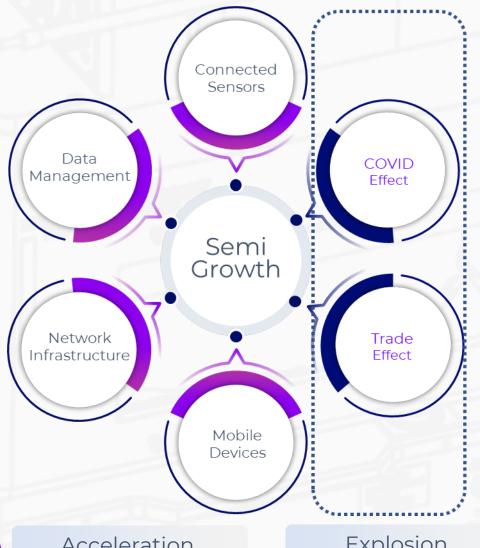


Cloud Data









2 Beyond Capacity **Performance Demand**



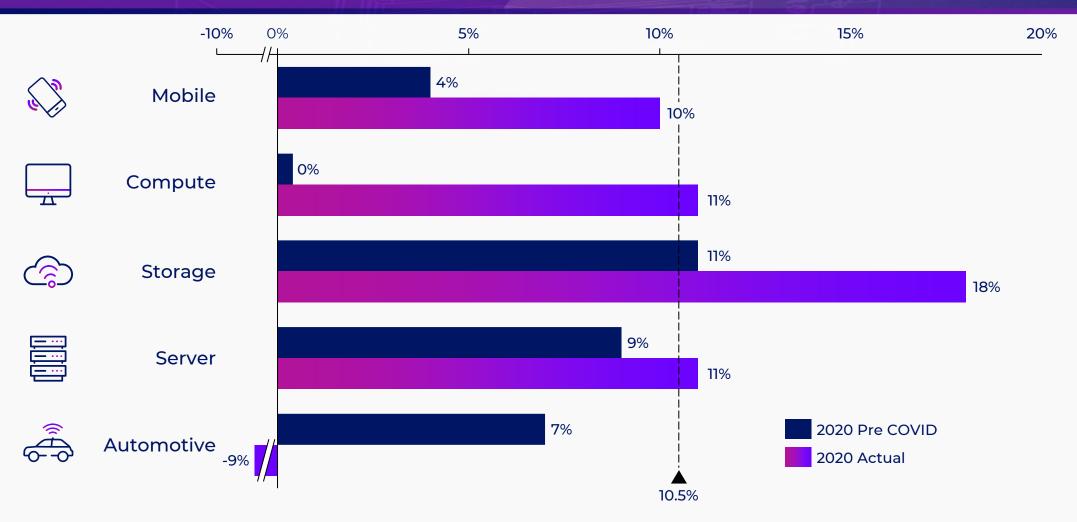
Acceleration

Explosion

Enablement

Semiconductor 2020 – COVID Impact

Semiconductor Segments in 2020 – Pre Covid Prediction vs Actual Growth, %





Increase in National Investment in Semi

Government Incentives



CHIPs for America Act



Made in China 2025



2030 Digital Compass



InvesTaiwan



System chips vision and strategy



Key Semi Applications

Growth & Size



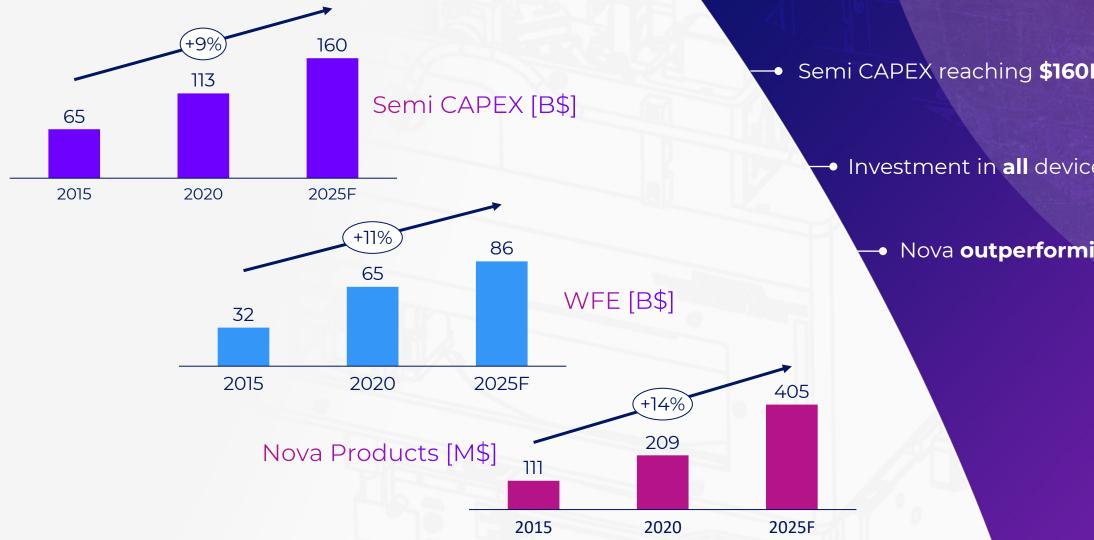


Silicon Content Increase

Data Video Game Driver Mobile Storage Consoles Assistance L1/2 to L4/5 **Trend** Data Explosion Cloud & Next Gen 4G to 5G Content +30% +30% +150% +200%



CAPEX and WFE Outlook



Semi CAPEX reaching \$160B in 2025

→ Investment in **all** device segments

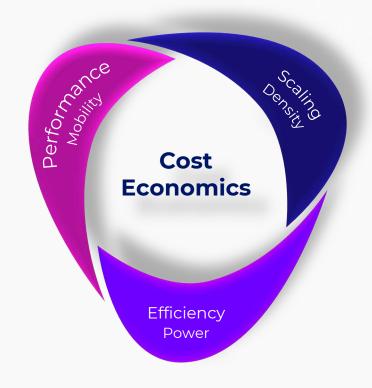
Nova outperforming the market



NOV

Semi Technology Inflections

Architectures and Materials



Packaging Schemes



Device Architecture



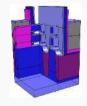
Materials Engineering



3D Memory Structures



Device Scaling



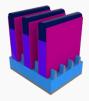




Device Technology Roadmap Trends and Challenges

2021 > 2022 > 2023 > 2024 > 2025

Logic



Transition to Nanosheet devices



Challenges

- Increased complexity
- More CDs
- Individual properties measurement
- New materials, new metals in BEOL

NAND



3D scaling to multi/triple deck 3D-NAND



- CMOS under array/wafer bonding
- Multi/triple-deck high aspect ratio
- Structural and Material challenges

DRAM



Continued scaling to 1c/1d DRAM



- Scaling, process margin (overlay and CD)
- Wafer edge yield, storage capacitor
- CDs, films, profiles, residues, defectivity





Dimensional Metrology

Integrated Metrology

NOVA i570



NOVA ASTERA



- Extending Nova IM Leadership
- Targeting high volume production and R&D of next generation nodes
- Adopted by all leading customers

Stand Alone Metrology



- · A New Dimension in Optical CD
- Addressing advanced metrology challenges in logic,3D-NAND and DRAM
- Adopted by leading logic and memory customers



Materials Metrology

X-Ray Metrology

NOVA VERAFLEX IV



- Adopted by all the leading customers
- Marking Nova's materials metrology leadership

Optical Metrology

NOVA ELIPSON



- In-line Raman Spectroscopy
- Adopted by leading logic and memory customers



Modeling & Fleet SW Solutions

Physical and Mathematical Modeling

NOVA MARS



NOVA FIT



- Holistic Approach to Modeling Driven Insights
- Unique algorithms solutions and Machine learning leadership

Fleet SW Solutions

Fleet Management



- Central management
- Performance monitoring
- Big data analytics







It's all About Technology and Differentiation

Dr. Shay Wolfling, CTO



Dr. Shay WolflingChief Technology Officer



Joined Nova as CTO in 2011.

R&D manager at KLA-Tencor-Belgium, leading multidisciplinary metrology & inspection projects.

Founder and VP R&D of Nano-Or-Technologies, a start-up company with a proprietary 3D optical technology, acquired in 2005.

PhD in physics from the Hebrew University.



Outline

Key Challenges

Unique Technology Solutions

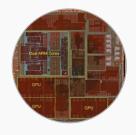
Future Plans



Expanding Challenges at the Advanced Nodes

Process Challenges ⇒ Metrology Opportunity







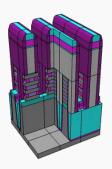
R&D cycles

More steps & higher sampling

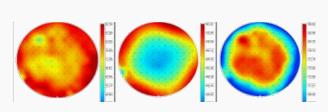
Tighter specs as design rule shrinks

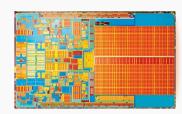
In-die & complex structures

New materials









Dimensional complexity increases: 3D devices

High aspect ratio structures

Local variation is critical: local density, Z Profiling

Monitoring more parameters → broader metrology scope





Key Challenges

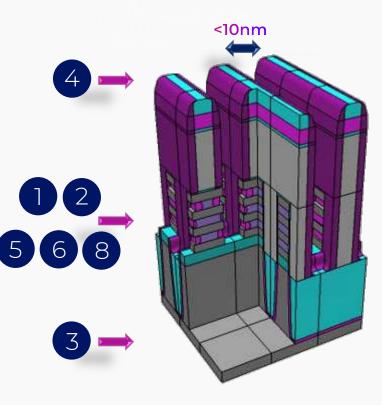
Across all device segments

Dimensional

- Multiple Nanowires shapes, spacing & thickness
- 2. Thin deposition surrounding nanosheets
- 3. Buried structures
- 4. Local topography variations

Material

- 5. Si/SiGe uniformity
- 6. SiGe residues
- 7. Doping control
- 8. Stress & strain on multiple nanosheets



Overlay

Silt
TCD

Silt
MCD

4

5

Silt
BCD

2

2

>200 Tiers
50 nm
Single tier
thickness

Dimensional:

- 1. HAR channel-hole full profile
- 2. Underlying logic cell (CuA)
- 3. Bottom parameters
- 4. Tiers and liner thickness
- 5. Multi-deck alignment

Material:

- 5. Dielectric composition & thickness control
- 6. Channel Poly Si crystallinity & grain size
- 7. Channel sidewall
- 3. Chemical residues





Core Technology

Spectral Reflectometry (SR) •

X-Ray Photoelectron Spectroscopy (XPS) •

X-Ray Fluorescence (XRF) •

Physical Modeling •

Fleet Management •

Disruptive Technology

Spectral Interferometry (SI)

Multi Channel Integrated Metrology

Advanced X-Ray

Innovative

Approach

to Address

Future Needs

Raman Spectroscopy

Mathematical Modeling & Big Data





Unique Technology Solutions

Dimensional

Critical Dimensions



Multi-Channel Integrated Metrology
Stand Alone performance in IM



Spectral InterferometryOCD Full Wavefront Metrology

Materials

Material Properties



X-Ray: XPS and XRF
In-Line composition & thickness



Optical: Raman Spectroscopy
In-Line stress / strain and crystallinity

Software & Algo

- Physical & Machine Learning Models
- Big Data Analytics





Physical & Mathematical Modeling

Combining all types of modeling



Cloud Based Fleet Management

Smart connectivity



Multi-Channel Integrated Metrology

World-Leading IM Performance



Stand-alone performance in Integrated Metrology form factor

- World's first IM with both oblique and normal incidence spectral information
- Stand-alone level performance: accuracy, sensitivity, parameters de-correlation
- Algo: dedicated modeling and ML package

Multiple use-cases

- R&D and pilot
- Complex CMP & etch layers
- Ultra-thin film
- Residue detection

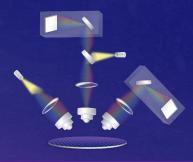




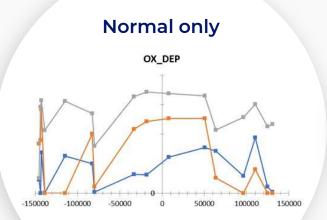


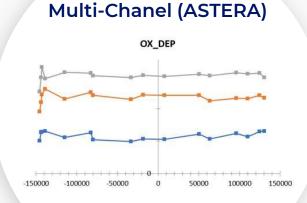
Multi-Channel Integrated Metrology

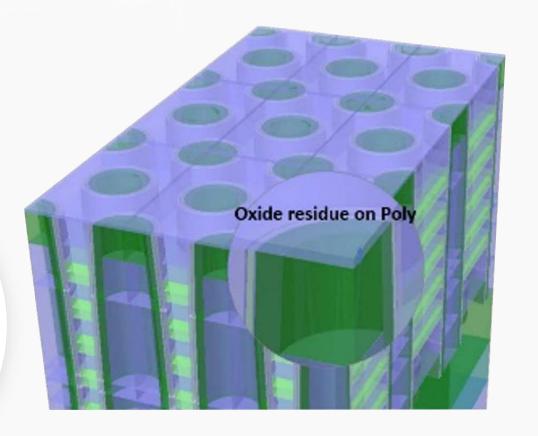
Case Study: Residue Detection in 3D NAND



- Demonstrated measurement sensitivity of below 20A
- Oblique channel as enabler to solve thin film on structure
- Improved accuracy and stable WiW variation
- 50% precision improvement VS normal only









Spectral Interferometry (SI)

Unique Optical CD Technology: Hardware & Software



SI

Added on top of advanced Reflectometry (SR) & Ellipsometry (SE)

New Data

Extract complete wave-front of measured sample (inaccessible by other methods)

Unique HW

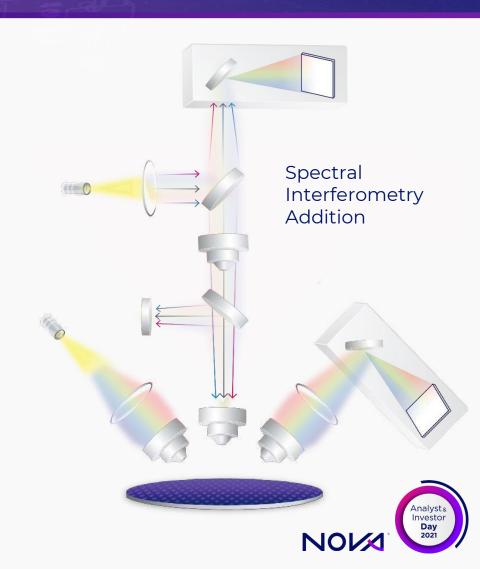
"Interferometry-like"

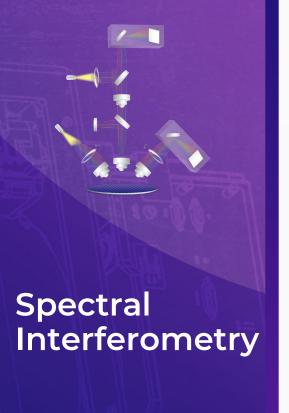
HW-SW Synergy

Proprietary algorithms using unique information (physical & mathematical modeling)

Synergy Enables

- Depth-profiling and underlayer filtering
- Enhanced performance on multiple use-cases

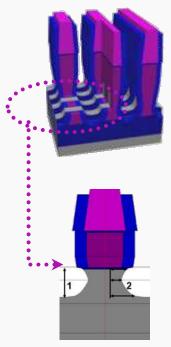




Example Use Cases

Unique profile information

Logic Source/ Drain etch

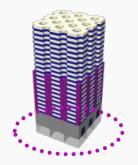


Underlayer filtering depth-based separation

Top deck applications

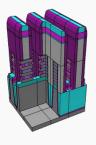


CMOS underlayer architecture



Depth-based separation

Individual Nanosheet properties (*)





XPS In-Line for Materials Metrology

The Market Standard for Ultra Thin Films



XPS

Inline non-destructive X-Ray for composition & thickness (World unique)

Beyond optics

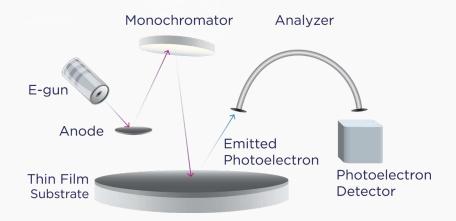
Precise control of ultra-thin films (e.g. HfO), enabling accurate Vt tuning

XRF

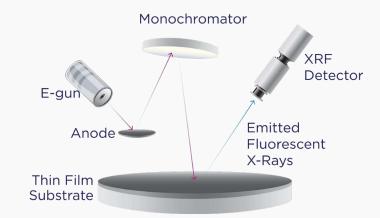
Simultaneous measurement for complex multi-stacks (e.g. SiGeB)

In-die on-product measurement of advanced DRAM and HAR 3DNAND (e.g. SiON)

Enabling process innovation – pattern selectivity and partial coverage in **Selective Deposition**



Non-Destructive



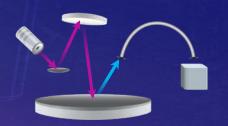




XPS for Materials Metrology

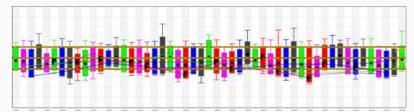
TiAl TiN SiO

Example Use Cases

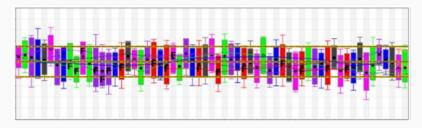


Nanosheet: Thickness and composition control

Ti:Al % Composition Control

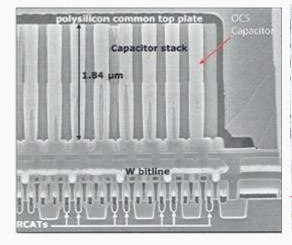


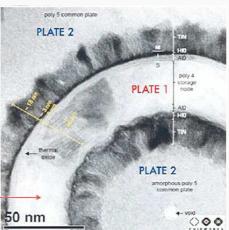
HfO Thickness Control



In line XPS and XRF deliver precise control of thickness and composition for complex gate stack film structures

DRAM: Complex High-K multi stack thickness control





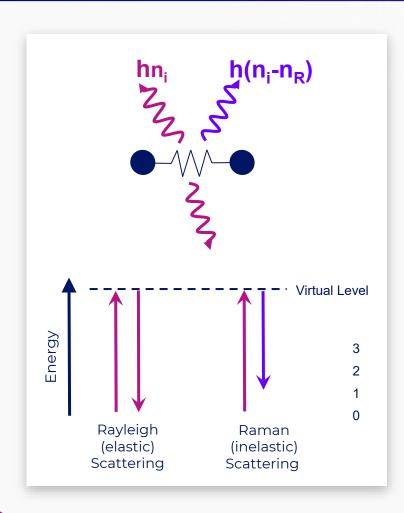
Only surface sensitive XPS can provide direct control of complex High-K dielectric stack in-die



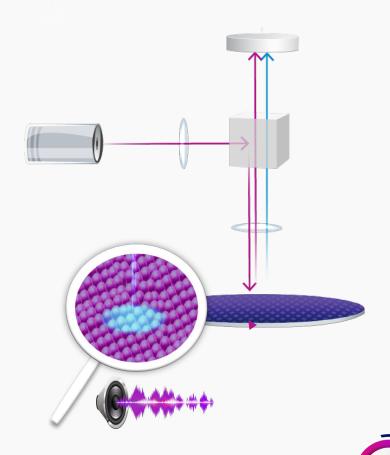
Raman Spectroscopy

For Materials Metrology





- Known powerful, optical technique for material characterization
- Small-spot on-structure metrology
- Sensitive to multiple material properties
- HVM-ready in-line Raman
- Algorithm and modeling: translating raw Raman spectra to SPC level data

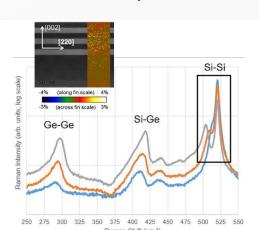




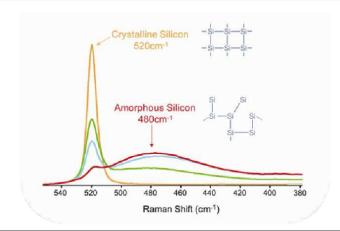
Raman Application Space

Validated by Leading Logic & Memory Customers

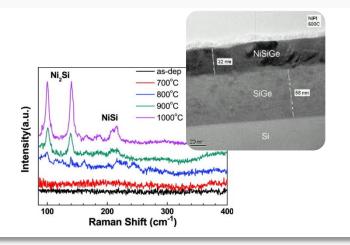
Strain in Channel and Source/ Drain*



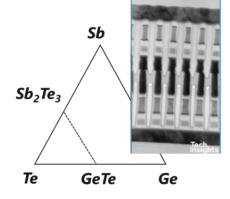
Crystallinity



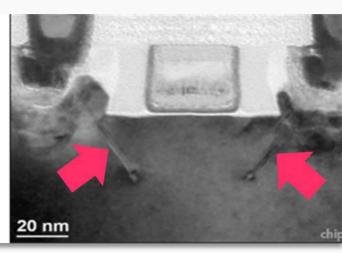
Phases and Grain-size







Defectivity





From Lab to Fab

A Complex Journey



Automation

- Fully automated HW and measurement sequence
- Recipe-driven 300mm wafers

HVM Worthy

- Fab connectivity for statistical process control
- Non-destructive

Peak Performance

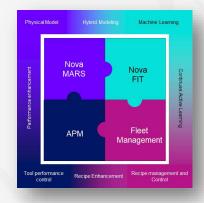
- High throughput, accuracy & repeatability
- Algorithm suite for material information analysis







Comprehensive Modeling



Benefits

- Accuracy & robustness → tighter process specs
- Reduce (destructive) reference → time to market
- Expand applications → more process control
- More parameters → deeper process insights

Unique Directions: Physical Modeling with Machine Learning













Physical Modeling

Nova Unique Reference

External Reference

SI, Raman, XPS, Multichannel IM

TEM, E-test

Nova Machine Learning

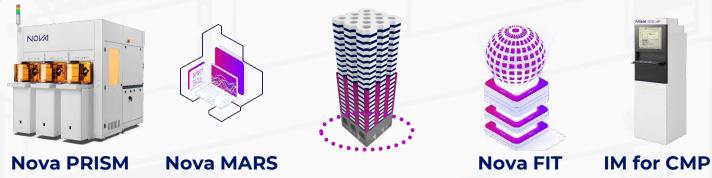




Software & Hardware Synergy

The Best of Both Worlds

- Unique HW & dedicated algorithms
- Cross platform synergy
- Continuously and actively optimize machine learning models



Under layer filtering via PRISM SI – Robust in-die solution for multi deck and CuA – Enhanced CMP control



Enhancing IM with XPS data via dedicated Machine Learning



Summary

Unique Technologies to Answer Key Challenges



NOVA PRISM

Spectral Interferometry



NOVA ASTERA

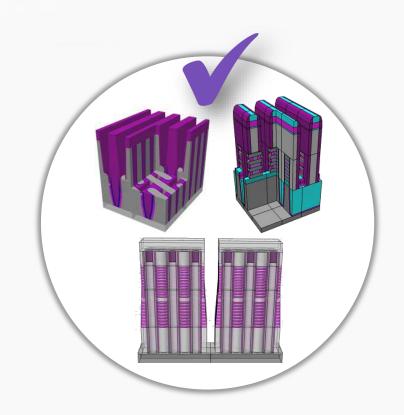
Multi-Channel Integrated Metrology



Nova MARS

Nova FIT

Physical & Mathematical modeling





XPS and XRF



NOVA ELIPSON

Optical: Raman Spectroscopy

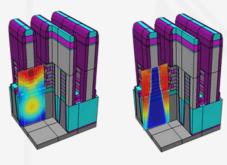


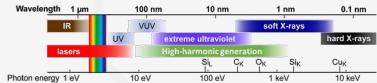




Future Directions

Dimensional

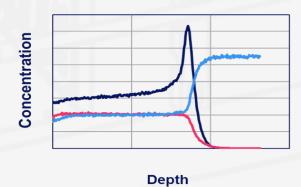




Different energy sources probe different dimensions of the structure

Materials

Boron Distribution Profile in SiGe



Depth-profile measurement

-Boron -Germanium -Silicon

Software and Algorithms



Comprehensive Modeling – Physical and Mathematical





Closing Remarks

Eitan Oppenhaim, President & CEO



Key Takeaways

Positioned for Continuous Growth



Growing demand for IC drives capacity & Increasing complexity
Increasing need for advanced metrology solutions



Unique and disruptive technology portfolio

Driving a stronger position and expanding TAM



Solid operational model

Supports clear strategy for growth



Proven performance towards Nova 500

Outperforming the Industry



Cultural elevation with new CSR strategy

Combining businesses ethics with culture and social conciseness











Thank You